

SLOVENSKI STANDARD

SIST EN IEC 60749-22-2:2026

01-marec-2026

Nadomešča:

SIST EN 60749-22:2004

**Polprevodniški elementi - Metode za mehansko in klimatsko preskušanje - 22-2.
del: Moč vezi - Preskusne metode za strižno vezavo žice (IEC 60749-22-2:2025)**

Semiconductor devices - Mechanical and climatic test methods - Part 22-2: Bond strength - Wire bond shear test methods (IEC 60749-22-2:2025)

Halbleiterbauelemente - Mechanische und klimatische Prüfverfahren –Teil 22:
Kontaktfestigkeit - Drahtbond-Scherprüfverfahren (IEC 60749-22-2:2025)

Dispositifs à semiconducteurs - Méthodes d'essais mécaniques et climatiques - Partie 22
-2: Robustesse des contacts soudés - Méthodes d'essais de cisaillement des contacts
soudés par fil (IEC 60749-22-2:2025)

Ta slovenski standard je istoveten z: EN IEC 60749-22-2:2026

ICS:

19.020	Preskuševalni pogoji in postopki na splošno	Test conditions and procedures in general
31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general

SIST EN IEC 60749-22-2:2026

en

EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN IEC 60749-22-2

January 2026

ICS 31.080.01

Supersedes EN 60749-22:2003 (partially)

English Version

**Semiconductor devices - Mechanical and climatic test methods -
Part 22-2: Bond strength - Wire bond shear test methods
(IEC 60749-22-2:2025)**

Dispositifs à semiconducteurs - Méthodes d'essais
mécaniques et climatiques - Partie 22-2: Robustesse des
contacts soudés - Méthodes d'essais de cisaillement des
contacts soudés par fil
(IEC 60749-22-2:2025)

Halbleiterbauelemente - Mechanische und klimatische
Prüfverfahren - Teil 22: Kontaktfestigkeit - Drahtbond-
Scherprüfverfahren
(IEC 60749-22-2:2025)

This European Standard was approved by CENELEC on 2025-12-31. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Republic of North Macedonia, Romania, Serbia, Slovakia, Slovenia, Spain, Sweden, Switzerland, Türkiye and the United Kingdom.



European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 60749-22-2:2026 (E)**European foreword**

The text of document 47/2959/FDIS, future edition 1 of IEC 60749-22-2, prepared by TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60749-22-2:2026.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2027-01-31 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2029-01-31 document have to be withdrawn

This document, together with EN IEC 60749-22-1:2026, supersedes EN 60749-22:2003.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

This document is read in conjunction with EN IEC 60749-22-1:2026.

Any feedback and questions on this document should be directed to the users' national committee. A complete listing of these bodies can be found on the CENELEC website.

iTeh Standards
Endorsement notice
(<https://standards.iteh.ai>)

The text of the International Standard IEC 60749-22-2:2025 was approved by CENELEC as a European Standard without any modification.

[SIST EN IEC 60749-22-2:2026](https://standards.iteh.ai/catalog/standards/sist/ce4d154e-be77-4b25-90c5-de84bd7a232f/sist-en-iec-60749-22-2-2026)

<https://standards.iteh.ai/catalog/standards/sist/ce4d154e-be77-4b25-90c5-de84bd7a232f/sist-en-iec-60749-22-2-2026>

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60749-22-1	-	Semiconductor devices - Mechanical and climatic test methods - Part 22-1: Bond strength - Wire bond pull test methods	-	-

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